APPARATUS AND METHOD FOR MOUNTING SEMICONDUCTOR CHIPS ON A SUBSTRATE

ABSTRACT

An apparatus for mounting semiconductor chips (1) on a substrate (2) with which the semiconductor chips (1) are presented on a foil (4) clamped in a frame (3) at a first location A comprises a chip gripper (10) for the transport of the semiconductor chip (1) presented at the first location A to a second location located on the substrate (2), a movable table (5) for accepting the frame (3), a chip ejector (6) arranged underneath the foil (4) at the first location A the upper surface (15) of which facing towards the foil (4) has holes (7) connected to a vacuum source, as well as a measuring camera (9) directed at the first location A for establishing the position of the presented semiconductor chip (1). Correction of a possible position deviation of the presented semiconductor chip (1) from its set position takes place in accordance with the invention in that the foil (4) is secured by the chip ejector (6) by means of vacuum and then at least the upper surface (15) of the chip ejector (6) facing towards the foil (4) is moved in the plane running parallel to the under side of the foil.

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